

## Refine Search

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### Search Results -

Terms	Documents
L2 and amino acid	90

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**Database:** US Pre-Grant Publication Full-Text Database  
 US Patents Full-Text Database  
 US OCR Full-Text Database  
 EPO Abstracts Database  
 JPO Abstracts Database  
 Derwent World Patents Index  
 IBM Technical Disclosure Bulletins

**Search:** L4

Recall Text
Clear
Interrupt

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### Search History

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DATE: Friday, January 04, 2008    [Purge Queries](#)    [Printable Copy](#)    [Create Case](#)

<u>Set</u>	<u>Hit</u>	<u>Set</u>
<u>Name</u>	<u>Count</u>	<u>Name</u>
side by side		result set
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ		
L4 L2 and amino acid	90	L4
L3 L1 and amino acid	124	L3
L2 L1 and (polishing or planarizing or cmp or planarization) with (copper or cu or tantalum or ta)	198	L2
L1 (catechol or pyrogallol or gallic acid or tannic acid or polyphenol or tannin) and abrasive and (oxidizer or oxidizing agent) and (benzotriazole or bta)	313	L1

END OF SEARCH HISTORY